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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	I²C, IRSCI, SCI, SPI
Peripherals	LED, LVD, POR, PWM
Number of I/O	30
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	42-SDIP (0.600", 15.24mm)
Supplier Device Package	42-PDIP
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc908ap32acbe

- Timebase module
- Serial communications interface module 1 (SCI)
- Serial communications interface module 2 (SCI) with infrared (IR) encoder/decoder
- Serial peripheral interface module (SPI)
- System management bus (SMBus), version 1.0/1.1 (multi-master IIC bus)
- 8-channel, 10-bit analog-to-digital converter (ADC)
- $\overline{\text{IRQ1}}$ external interrupt pin with integrated pullup
- $\overline{\text{IRQ2}}$ external interrupt pin with programmable pullup
- 8-bit keyboard wakeup port with integrated pullup
- 32 general-purpose input/output (I/O) pins:
  - 31 shared-function I/O pins
  - 8 LED drivers (sink)
  - 6×25mA open-drain I/O with pullup
- Low-power design (fully static with stop and wait modes)
- Master reset pin (with integrated pullup) and power-on reset
- System protection features
  - Optional computer operating properly (COP) reset, driven by internal RC oscillator
  - Low-voltage detection with optional reset or interrupt
  - Illegal opcode detection with reset
  - Illegal address detection with reset
- 48-pin low quad flat pack (LQFP), 44-pin quad flat pack (QFP), and 42-pin shrink dual-in-line package (SDIP)
- Specific features of the MC68HC908AP64A in 42-pin SDIP are:
  - 30 general-purpose I/Os only
  - External interrupt on $\overline{\text{IRQ1}}$ only

Features of the CPU08 include the following:

- Enhanced HC05 programming model
- Extensive loop control functions
- 16 addressing modes (eight more than the HC05)
- 16-bit Index register and stack pointer
- Memory-to-memory data transfers
- Fast 8×8 multiply instruction
- Fast 16/8 divide instruction
- Binary-coded decimal (BCD) instructions
- Optimization for controller applications
- Efficient C language support

1.3 MCU Block Diagram

Figure 1-1 shows the structure of the MC68HC908AP64A.

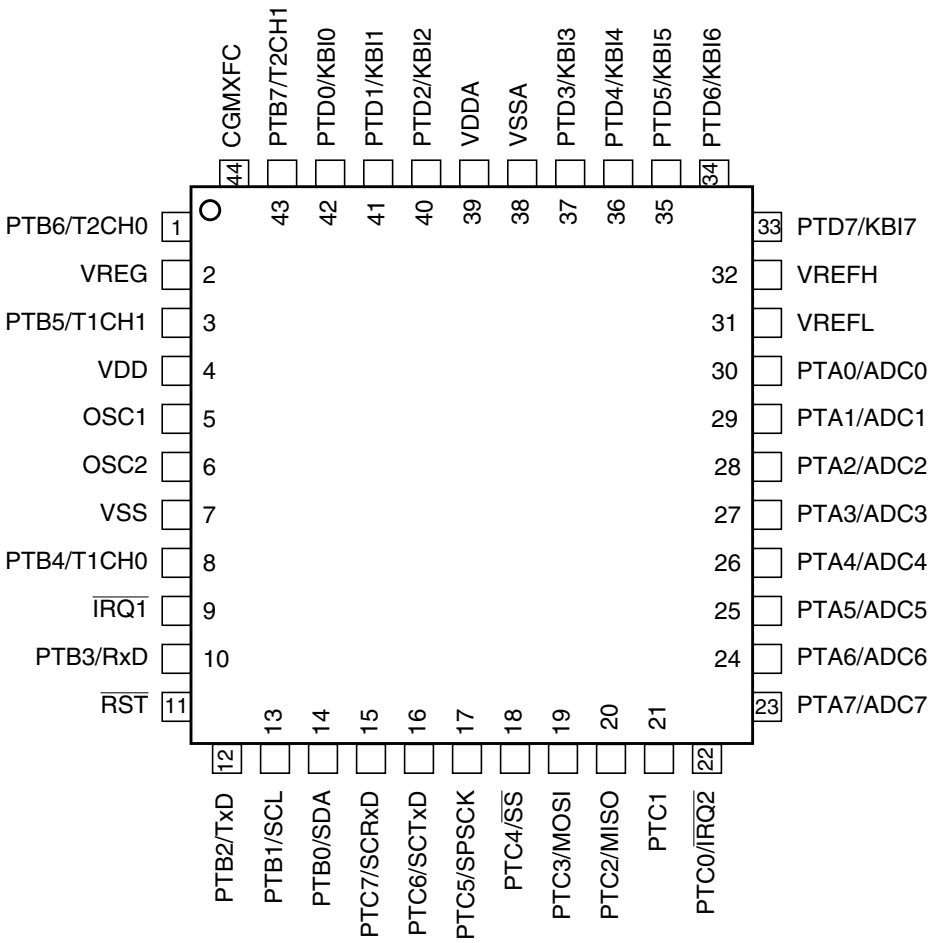


Figure 1-3. 44-Pin QFP Pin Assignments

Before processing an interrupt, the CPU uses five bytes of the stack to save the contents of the CPU registers.

NOTE

For M6805 compatibility, the H register is not stacked.

During a subroutine call, the CPU uses two bytes of the stack to store the return address. The stack pointer decrements during pushes and increments during pulls.

NOTE

Be careful when using nested subroutines. The CPU may overwrite data in the RAM during a subroutine or during the interrupt stacking operation.

2.5 FLASH Memory

This sub-section describes the operation of the embedded FLASH memory. This memory can be read, programmed, and erased from a single external supply. The program and erase operations are enabled through the use of an internal charge pump.

Device	FLASH Memory Size (Bytes)	Memory Address Range
MC68HC908AP64A	62,368	$0860–$FBFF
MC68HC908AP32A	32,768	$0860–$885F
MC68HC908AP16A	16,384	$0860–$485F
MC68HC908AP8A	8,192	$0860–$285F

2.5.1 Functional Description

The FLASH memory consists of an array of 62,368 bytes for user memory plus a block of 48 bytes for user interrupt vectors and one byte for the mask option register. *An erased bit reads as logic 1 and a programmed bit reads as a logic 0.* The FLASH memory page size is defined as 512 bytes, and is the minimum size that can be erased in a page erase operation. Program and erase operations are facilitated through control bits in FLASH control register (FLCR). The address ranges for the FLASH memory are:

- $0860–$FBFF; user memory, 62,368 bytes
- $FFD0–$FFFF; user interrupt vectors, 48 bytes
- $FFCF; mask option register

Programming tools are available from Freescale. Contact your local Freescale representative for more information.

NOTE

A security feature prevents viewing of the FLASH contents.[1]

1. No security feature is absolutely secure. However, Freescale's strategy is to make reading or copying the FLASH difficult for unauthorized users.

3.2 Functional Description

The configuration registers and the mask option register are used in the initialization of various options. These two types of registers are configured differently:

- Configuration registers — Write-once registers after reset
- Mask option register — FLASH register (write by programming)

The configuration registers can be written once after each reset. All of the configuration register bits are cleared during reset. Since the various options affect the operation of the MCU, it is recommended that these registers be written immediately after reset. The configuration registers are located at $001D and $001F. The configuration registers may be read at anytime.

NOTE

The CONFIG registers are not in the FLASH memory but are special registers containing one-time writable latches after each reset. Upon a reset, the CONFIG registers default to predetermined settings as shown in Figure 3-2 and Figure 3-3.

The mask option register (MOR) is used for selecting one of the three clock options for the MCU. The MOR is a byte located in FLASH memory, and is written to by a FLASH programming routine.

3.3 Configuration Register 1 (CONFIG1)

Address: $001F

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVIREGD	SSREC	STOP	COPD
Reset:	0	0	0	0	0	0	0	0

Figure 3-2. Configuration Register 1 (CONFIG1)

COPRS — COP Rate Select Bit

COPRS selects the COP time out period. Reset clears COPRS. (See Chapter 19 Computer Operating Properly (COP).)

1 = COP time out period = 8176 ICLK cycles
0 = COP time out period = 262,128 ICLK cycles

LVISTOP — LVI Enable in Stop Mode Bit

When the LVIPWRD or LVIREGD bit is clear, setting the LVISTOP bit enables the LVI to operate during stop mode. Reset clears LVISTOP. (See Chapter 20 Low-Voltage Inhibit (LVI).)

1 = LVI enabled during stop mode
0 = LVI disabled during stop mode

NOTE

If LVISTOP=0, set LVIRSTD=1 before entering stop mode.

LVIRSTD — LVI Reset Disable Bit

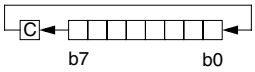
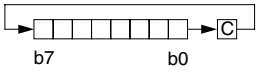
LVIRSTD disables the reset signal from the LVI module. (See Chapter 20 Low-Voltage Inhibit (LVI).)

1 = LVI module resets disabled
0 = LVI module resets enabled

Table 4-1. Instruction Set Summary

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z	C				
BSR *rel*	Branch to Subroutine	PC ← (PC) + 2; push (PCL) SP ← (SP) – 1; push (PCH) SP ← (SP) – 1 PC ← (PC) + *rel*	–	–	–	–	–	–	REL	AD	rr	4
CBEQ *opr,rel* CBEQA #*opr,rel* CBEQX #*opr,rel* CBEQ *opr*,X+,*rel* CBEQ X+,*rel* CBEQ *opr*,SP,*rel*	Compare and Branch if Equal	PC ← (PC) + 3 + rel ? (A) – (M) = $00 PC ← (PC) + 3 + rel ? (A) – (M) = $00 PC ← (PC) + 3 + rel ? (X) – (M) = $00 PC ← (PC) + 3 + rel ? (A) – (M) = $00 PC ← (PC) + 2 + rel ? (A) – (M) = $00 PC ← (PC) + 4 + rel ? (A) – (M) = $00	–	–	–	–	–	–	DIR IMM IMM IX1+ IX+ SP1	31 41 51 61 71 9E61	dd rr ii rr ii rr ff rr rr ff rr	5 4 4 5 4 6
CLC	Clear Carry Bit	C ← 0	–	–	–	–	–	0	INH	98		1
CLI	Clear Interrupt Mask	I ← 0	–	–	0	–	–	–	INH	9A		2
CLR *opr* CLRA CLRX CLRH CLR *opr*,X CLR ,X CLR *opr*,SP	Clear	M ← $00 A ← $00 X ← $00 H ← $00 M ← $00 M ← $00 M ← $00	0	–	–	0	1	–	DIR INH INH INH IX1 IX SP1	3F 4F 5F 8C 6F 7F 9E6F	dd ff ff	3 1 1 1 3 2 4
CMP #*opr* CMP *opr* CMP *opr* CMP *opr*,X CMP *opr*,X CMP ,X CMP *opr*,SP CMP *opr*,SP	Compare A with M	(A) – (M)	↕	–	–	↕	↕	↕	IMM DIR EXT IX2 IX1 IX SP1 SP2	A1 B1 C1 D1 E1 F1 9EE1 9ED1	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
COM *opr* COMA COMX COM *opr*,X COM ,X COM *opr*,SP	Complement (One's Complement)	M ← ($\overline{M}$) = $FF – (M) A ← ($\overline{A}$) = $FF – (M) X ← ($\overline{X}$) = $FF – (M) M ← ($\overline{M}$) = $FF – (M) M ← ($\overline{M}$) = $FF – (M) M ← ($\overline{M}$) = $FF – (M)	0	–	–	↕	↕	1	DIR INH INH IX1 IX SP1	33 43 53 63 73 9E63	dd ff ff	4 1 1 4 3 5
CPHX #*opr* CPHX *opr*	Compare H:X with M	(H:X) – (M:M + 1)	↕	–	–	↕	↕	↕	IMM DIR	65 75	ii ii+1 dd	3 4
CPX #*opr* CPX *opr* CPX *opr* CPX ,X CPX *opr*,X CPX *opr*,X CPX *opr*,SP CPX *opr*,SP	Compare X with M	(X) – (M)	↕	–	–	↕	↕	↕	IMM DIR EXT IX2 IX1 IX SP1 SP2	A3 B3 C3 D3 E3 F3 9EE3 9ED3	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
DAA	Decimal Adjust A	$(A)_{10}$	U	–	–	↕	↕	↕	INH	72		2

Table 4-1. Instruction Set Summary

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z	C				
PULH	Pull H from Stack	SP ← (SP + 1); Pull (H)	–	–	–	–	–	–	INH	8A		2
PULX	Pull X from Stack	SP ← (SP + 1); Pull (X)	–	–	–	–	–	–	INH	88		2
ROL *opr* ROLA ROLX ROL *opr*,X ROL ,X ROL *opr*,SP	Rotate Left through Carry		↕	–	–	↕	↕	↕	DIR INH INH IX1 IX SP1	39 49 59 69 79 9E69	dd ff ff	4 1 1 4 3 5
ROR *opr* RORA RORX ROR *opr*,X ROR ,X ROR *opr*,SP	Rotate Right through Carry		↕	–	–	↕	↕	↕	DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	dd ff ff	4 1 1 4 3 5
RSP	Reset Stack Pointer	SP ← $FF	–	–	–	–	–	–	INH	9C		1
RTI	Return from Interrupt	SP ← (SP) + 1; Pull (CCR) SP ← (SP) + 1; Pull (A) SP ← (SP) + 1; Pull (X) SP ← (SP) + 1; Pull (PCH) SP ← (SP) + 1; Pull (PCL)	↕	↕	↕	↕	↕	↕	INH	80		7
RTS	Return from Subroutine	SP ← SP + 1; Pull (PCH) SP ← SP + 1; Pull (PCL)	–	–	–	–	–	–	INH	81		4
SBC #*opr* SBC *opr* SBC *opr* SBC *opr*,X SBC *opr*,X SBC ,X SBC *opr*,SP SBC *opr*,SP	Subtract with Carry	A ← (A) – (M) – (C)	↕	–	–	↕	↕	↕	IMM DIR EXT IX2 IX1 IX SP1 SP2	A2 B2 C2 D2 E2 F2 9EE2 9ED2	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
SEC	Set Carry Bit	C ← 1	–	–	–	–	–	1	INH	99		1
SEI	Set Interrupt Mask	I ← 1	–	–	1	–	–	–	INH	9B		2
STA *opr* STA *opr* STA *opr*,X STA *opr*,X STA ,X STA *opr*,SP STA *opr*,SP	Store A in M	M ← (A)	0	–	–	↕	↕	–	DIR EXT IX2 IX1 IX SP1 SP2	B7 C7 D7 E7 F7 9EE7 9ED7	dd hh ll ee ff ff ff ee ff	3 4 4 3 2 4 5
STHX *opr*	Store H:X in M	(M:M + 1) ← (H:X)	0	–	–	↕	↕	–	DIR	35	dd	4
STOP	Enable Interrupts, Stop Processing, Refer to MCU Documentation	I ← 0; Stop Processing	–	–	0	–	–	–	INH	8E		1

NOTE

Route V_{SSA} carefully for maximum noise immunity and place bypass capacitors as close as possible to the package.

6.4.4 Oscillator Output Frequency Signal (CGMXCLK)

CGMXCLK is the oscillator output signal. It runs at the full speed of the oscillator, and is generated directly from the crystal oscillator circuit, the RC oscillator circuit, or the internal oscillator circuit.

6.4.5 CGM Reference Clock (CGMRCLK)

CGMRCLK is a buffered version of CGMXCLK, this clock is the reference clock for the phase-locked-loop circuit.

6.4.6 CGM VCO Clock Output (CGMVCLK)

CGMVCLK is the clock output from the VCO.

6.4.7 CGM Base Clock Output (CGMOUT)

CGMOUT is the clock output of the CGM. This signal goes to the SIM, which generates the MCU clocks. CGMOUT is a 50 percent duty cycle clock running at twice the bus frequency. CGMOUT is software programmable to be either the oscillator output, CGMXCLK, divided by two or the divided VCO clock, CGMPCLK, divided by two.

6.4.8 CGM CPU Interrupt (CGMINT)

CGMINT is the interrupt signal generated by the PLL lock detector.

6.5 CGM Registers

The following registers control and monitor operation of the CGM:

- PLL control register (PCTL)
  (See 6.5.1 PLL Control Register.)
- PLL bandwidth control register (PBWC)
  (See 6.5.2 PLL Bandwidth Control Register.)
- PLL multiplier select registers (PMSH and PMSL)
  (See 6.5.3 PLL Multiplier Select Registers.)
- PLL VCO range select register (PMRS)
  (See 6.5.4 PLL VCO Range Select Register.)
- PLL reference divider select register (PMDS)
  (See 6.5.5 PLL Reference Divider Select Register.)

6.8 Acquisition/Lock Time Specifications

The acquisition and lock times of the PLL are, in many applications, the most critical PLL design parameters. Proper design and use of the PLL ensures the highest stability and lowest acquisition/lock times.

6.8.1 Acquisition/Lock Time Definitions

Typical control systems refer to the acquisition time or lock time as the reaction time, within specified tolerances, of the system to a step input. In a PLL, the step input occurs when the PLL is turned on or when it suffers a noise hit. The tolerance is usually specified as a percent of the step input or when the output settles to the desired value plus or minus a percent of the frequency change. Therefore, the reaction time is constant in this definition, regardless of the size of the step input. For example, consider a system with a 5 percent acquisition time tolerance. If a command instructs the system to change from 0 Hz to 1 MHz, the acquisition time is the time taken for the frequency to reach 1 MHz ±50 kHz. 50 kHz = 5% of the 1 MHz step input. If the system is operating at 1 MHz and suffers a –100 kHz noise hit, the acquisition time is the time taken to return from 900 kHz to 1 MHz ±5 kHz. 5 kHz = 5% of the 100 kHz step input.

Other systems refer to acquisition and lock times as the time the system takes to reduce the error between the actual output and the desired output to within specified tolerances. Therefore, the acquisition or lock time varies according to the original error in the output. Minor errors may not even be registered. Typical PLL applications prefer to use this definition because the system requires the output frequency to be within a certain tolerance of the desired frequency regardless of the size of the initial error.

6.8.2 Parametric Influences on Reaction Time

Acquisition and lock times are designed to be as short as possible while still providing the highest possible stability. These reaction times are not constant, however. Many factors directly and indirectly affect the acquisition time.

The most critical parameter which affects the reaction times of the PLL is the reference frequency, f_{RDV}. This frequency is the input to the phase detector and controls how often the PLL makes corrections. For stability, the corrections must be small compared to the desired frequency, so several corrections are required to reduce the frequency error. Therefore, the slower the reference the longer it takes to make these corrections. This parameter is under user control via the choice of crystal frequency f_{XCLK} and the R value programmed in the reference divider. (See 6.3.3 PLL Circuits, 6.3.6 Programming the PLL, and 6.5.5 PLL Reference Divider Select Register.)

Another critical parameter is the external filter network. The PLL modifies the voltage on the VCO by adding or subtracting charge from capacitors in this network. Therefore, the rate at which the voltage changes for a given frequency error (thus change in charge) is proportional to the capacitance. The size of the capacitor also is related to the stability of the PLL. If the capacitor is too small, the PLL cannot make small enough adjustments to the voltage and the system cannot lock. If the capacitor is too large, the PLL may not be able to adjust the voltage in a reasonable time. (See 6.8.3 Choosing a Filter.)

Also important is the operating voltage potential applied to V_{DDA}. The power supply potential alters the characteristics of the PLL. A fixed value is best. Variable supplies, such as batteries, are acceptable if they vary within a known range at very slow speeds. Noise on the power supply is not acceptable, because it causes small frequency errors which continually change the acquisition time of the PLL.

Temperature and processing also can affect acquisition time because the electrical characteristics of the PLL change. The part operates as specified as long as these influences stay within the specified limits. External factors, however, can cause drastic changes in the operation of the PLL. These factors include noise injected into the PLL through the filter capacitor, filter capacitor leakage, stray impedances on the circuit board, and even humidity or circuit board contamination.

6.8.3 Choosing a Filter

As described in 6.8.2 Parametric Influences on Reaction Time, the external filter network is critical to the stability and reaction time of the PLL. The PLL is also dependent on reference frequency and supply voltage.

Either of the filter networks in Figure 6-10 is recommended when using a 4MHz reference clock (CGMRCLK). Figure 6-10 **(a)** is used for applications requiring better stability. Figure 6-10 **(b)** is used in low-cost applications where stability is not critical.

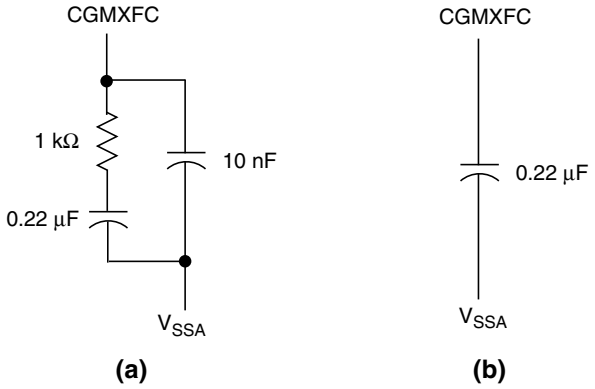
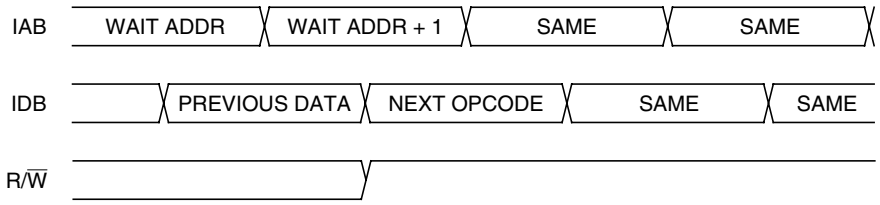


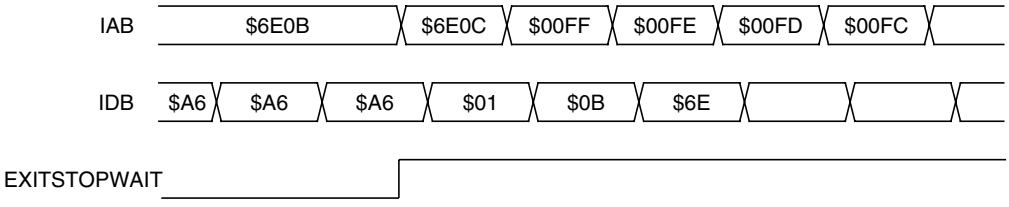
Figure 6-10. PLL Filter



NOTE: Previous data can be operand data or the WAIT opcode, depending on the last instruction.

Figure 7-15. Wait Mode Entry Timing

Figure 7-16 and Figure 7-17 show the timing for WAIT recovery.



NOTE: EXITSTOPWAIT = $\overline{\text{RST}}$ pin OR CPU interrupt OR break interrupt

Figure 7-16. Wait Recovery from Interrupt or Break

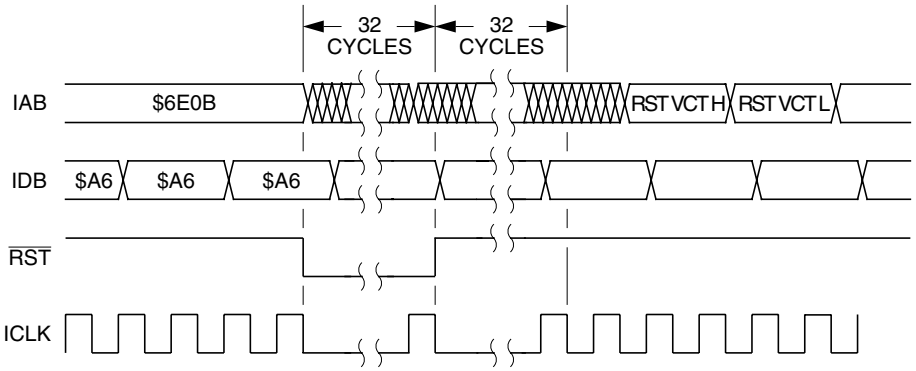


Figure 7-17. Wait Recovery from Internal Reset

7.6.2 Stop Mode

In stop mode, the SIM counter is reset and the system clocks are disabled. An interrupt request from a module can cause an exit from stop mode. Stacking for interrupts begins after the selected stop recovery time has elapsed. Reset or break also causes an exit from stop mode.

The SIM disables the clock generator module output (CGMOUT) in stop mode, stopping the CPU and peripherals. Stop recovery time is selectable using the SSREC bit in the configuration register 1 (CONFIG1). If SSREC is set, stop recovery is reduced from the normal delay of 4096 ICLK cycles down to 32. This is ideal for applications using canned oscillators that do not require long start-up times from stop mode.

NOTE

External crystal applications should use the full stop recovery time by clearing the SSREC bit.

9.4.4.2 Buffered PWM Signal Generation

Channels 0 and 1 can be linked to form a buffered PWM channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the pulse width of the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The TIM channel 0 registers initially control the pulse width on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the pulse width at the beginning of the next PWM period. At each subsequent overflow, the TIM channel registers (0 or 1) that control the pulse width are the ones written to last. TSC0 controls and monitors the buffered PWM function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

NOTE

In buffered PWM signal generation, do not write new pulse width values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered PWM signals.

9.4.4.3 PWM Initialization

To ensure correct operation when generating unbuffered or buffered PWM signals, use the following initialization procedure:

1. In the TIM status and control register (TSC):
   a. Stop the TIM counter by setting the TIM stop bit, TSTOP.
   b. Reset the TIM counter and prescaler by setting the TIM reset bit, TRST.
2. In the TIM counter modulo registers (TMODH:TMODL), write the value for the required PWM period.
3. In the TIM channel x registers (TCHxH:TCHxL), write the value for the required pulse width.
4. In TIM channel x status and control register (TSCx):
   a. Write 0:1 (for unbuffered output compare or PWM signals) or 1:0 (for buffered output compare or PWM signals) to the mode select bits, MSxB:MSxA. (See Table 9-3.)
   b. Write 1 to the toggle-on-overflow bit, TOVx.
   c. Write 1:0 (to clear output on compare) or 1:1 (to set output on compare) to the edge/level select bits, ELSxB:ELSxA. The output action on compare must force the output to the complement of the pulse width level. (See Table 9-3.)

   NOTE

   In PWM signal generation, do not program the PWM channel to toggle on output compare. Toggling on output compare prevents reliable 0% duty cycle generation and removes the ability of the channel to self-correct in the event of software error or noise. Toggling on output compare can also cause incorrect PWM signal generation when changing the PWM pulse width to a new, much larger value.
5. In the TIM status control register (TSC), clear the TIM stop bit, TSTOP.

Table 9-3. Mode, Edge, and Level Selection

MSxB:MSxA	ELSxB:ELSxA	Mode	Configuration
X0	00	Output preset	Pin under port control; initial output level high
X1	00		Pin under port control; initial output level low
00	01	Input capture	Capture on rising edge only
00	10		Capture on falling edge only
00	11		Capture on rising or falling edge
01	00	Output compare or PWM	Software compare only
01	01		Toggle output on compare
01	10		Clear output on compare
01	11		Set output on compare
1X	01	Buffered output compare or buffered PWM	Toggle output on compare
1X	10		Clear output on compare
1X	11		Set output on compare

NOTE

After initially enabling a TIM channel register for input capture operation, and selecting the edge sensitivity, clear CHxF to ignore any erroneous detection flags.

TOVx — Toggle On Overflow Bit

When channel x is an output compare channel, this read/write bit controls the behavior of the channel x output when the TIM counter overflows. When channel x is an input capture channel, TOVx has no effect.

Reset clears the TOVx bit.

1 = Channel x pin toggles on TIM counter overflow

0 = Channel x pin does not toggle on TIM counter overflow

NOTE

When TOVx is set, a TIM counter overflow takes precedence over a channel x output compare if both occur at the same time.

CHxMAX — Channel x Maximum Duty Cycle Bit

When the TOVx bit is at logic 1, setting the CHxMAX bit forces the duty cycle of buffered and unbuffered PWM signals to 100%. As Figure 9-11 shows, the CHxMAX bit takes effect in the cycle after it is set or cleared. The output stays at the 100% duty cycle level until the cycle after CHxMAX is cleared.

11.3 Pin Name Conventions

The generic names of the SCI I/O pins are:

- RxD (receive data)
- TxD (transmit data)

SCI I/O (input/output) lines are implemented by sharing parallel I/O port pins. The full name of an SCI input or output reflects the name of the shared port pin. Table 11-1 shows the full names and the generic names of the SCI I/O pins. The generic pin names appear in the text of this section.

Table 11-1. Pin Name Conventions

Generic Pin Names:	RxD	TxD
Full Pin Names:	PTB3/RxD	PTB2/TxD

NOTE

When the SCI is enabled, the TxD pin is an open-drain output and requires a pullup resistor to be connected for proper SCI operation.

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
$0013	SCI Control Register 1 (SCC1)	Read: Write:	LOOPS	ENSCI	TXINV	M	WAKE	ILTY	PEN	PTY
		Reset:	0	0	0	0	0	0	0	0
$0014	SCI Control Register 2 (SCC2)	Read: Write:	SCTIE	TCIE	SCRIE	ILIE	TE	RE	RWU	SBK
		Reset:	0	0	0	0	0	0	0	0
$0015	SCI Control Register 3 (SCC3)	Read:	R8	T8	DMARE	DMATE	ORIE	NEIE	FEIE	PEIE
		Write:								
		Reset:	U	U	0	0	0	0	0	0
$0016	SCI Status Register 1 (SCS1)	Read:	SCTE	TC	SCRF	IDLE	OR	NF	FE	PE
		Write:								
		Reset:	1	1	0	0	0	0	0	0
$0017	SCI Status Register 2 (SCS2)	Read:							BKF	RPF
		Write:								
		Reset:	0	0	0	0	0	0	0	0
$0018	SCI Data Register (SCDR)	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	Unaffected by reset							
$0019	SCI Baud Rate Register (SCBR)	Read:	0	0	SCP1	SCP0	R	SCR2	SCR1	SCR0
		Write:								
		Reset:	0	0	0	0	0	0	0	0

= Unimplemented R = Reserved U = Unaffected

Figure 11-1. SCI I/O Register Summary

11.4.1 Data Format

The SCI uses the standard non-return-to-zero mark/space data format illustrated in Figure 11-3.

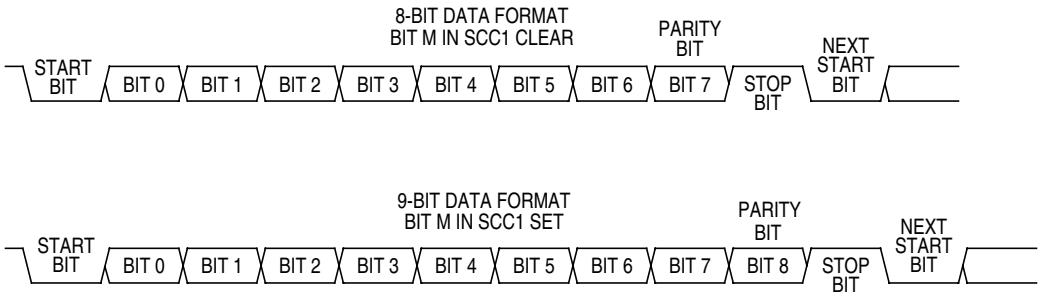


Figure 11-3. SCI Data Formats

11.4.2 Transmitter

Figure 11-4 shows the structure of the SCI transmitter.

The baud rate clock source for the SCI can be selected via the configuration bit, SCIBDSRC. Source selection values are shown in Figure 11-4.

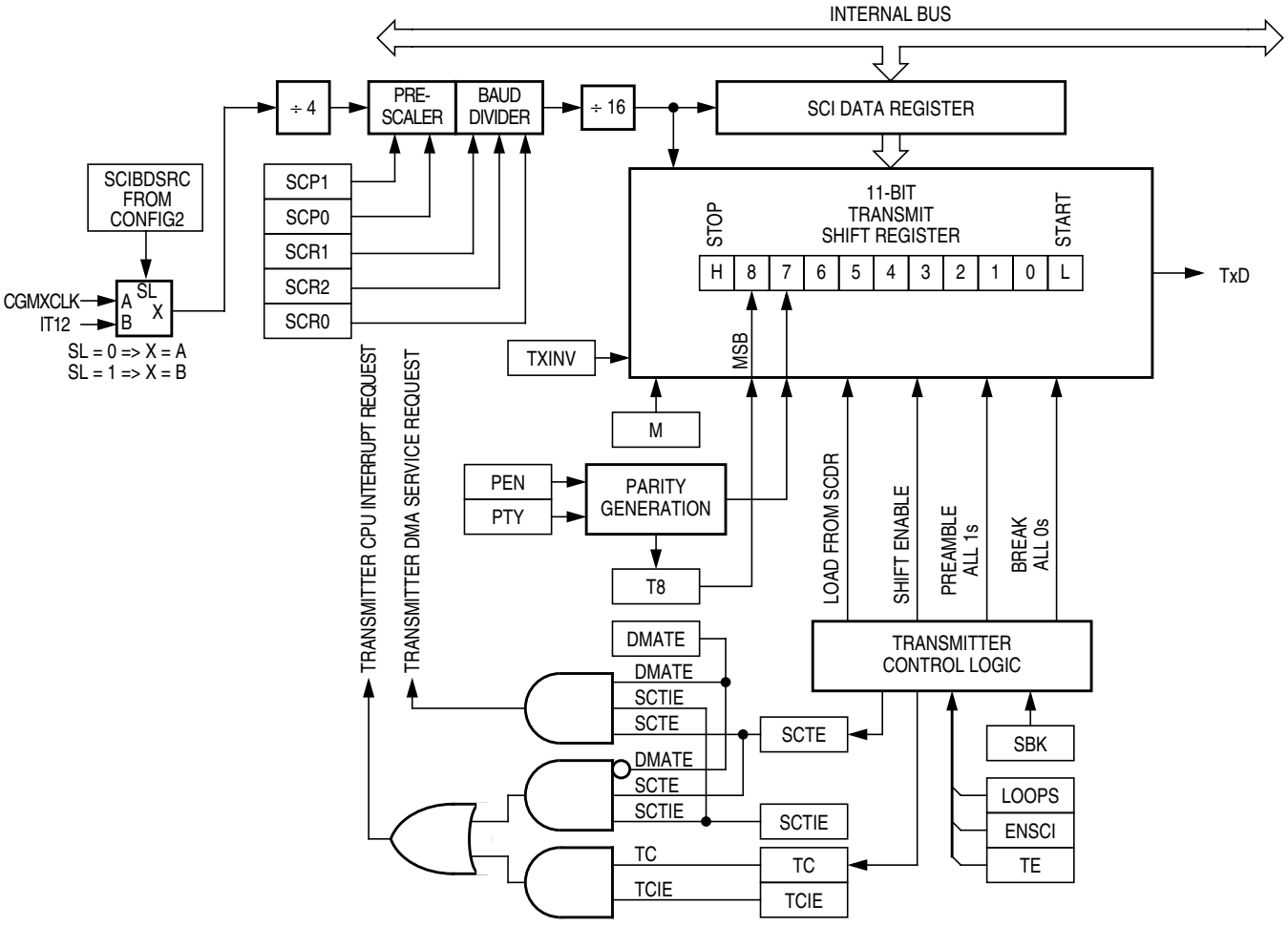


Figure 11-4. SCI Transmitter

11.8.7 SCI Baud Rate Register

The baud rate register (SCBR) selects the baud rate for both the receiver and the transmitter.

Address:	$0019	6	5	4	3	2	1	Bit 0
Read:	0	0	SCP1	SCP0	R	SCR2	SCR1	SCR0
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented R = Reserved

Figure 11-16. SCI Baud Rate Register (SCBR)

SCP1 and SCP0 — SCI Baud Rate Prescaler Bits

These read/write bits select the baud rate prescaler divisor as shown in Table 11-6. Reset clears SCP1 and SCP0.

Table 11-6. SCI Baud Rate Prescaling

SCP1 and SCP0	Prescaler Divisor (PD)
00	1
01	3
10	4
11	13

SCR2–SCR0 — SCI Baud Rate Select Bits

These read/write bits select the SCI baud rate divisor as shown in Table 11-7. Reset clears SCR2–SCR0.

Table 11-7. SCI Baud Rate Selection

SCR2, SCR1, and SCR0	Baud Rate Divisor (BD)
000	1
001	2
010	4
011	8
100	16
101	32
110	64
111	128

Use this formula to calculate the SCI baud rate:

$$\text{baud rate} = \frac{\text{SCI clock source}}{64 \times \text{PD} \times \text{BD}}$$

where:

SCI clock source = f_{BUS} or CGMXCLK
(selected by SCIBDSRC bit in CONFIG2 register)
PD = prescaler divisor
BD = baud rate divisor

12.5 SCI Functional Description

Figure 12-5 shows the structure of the SCI.

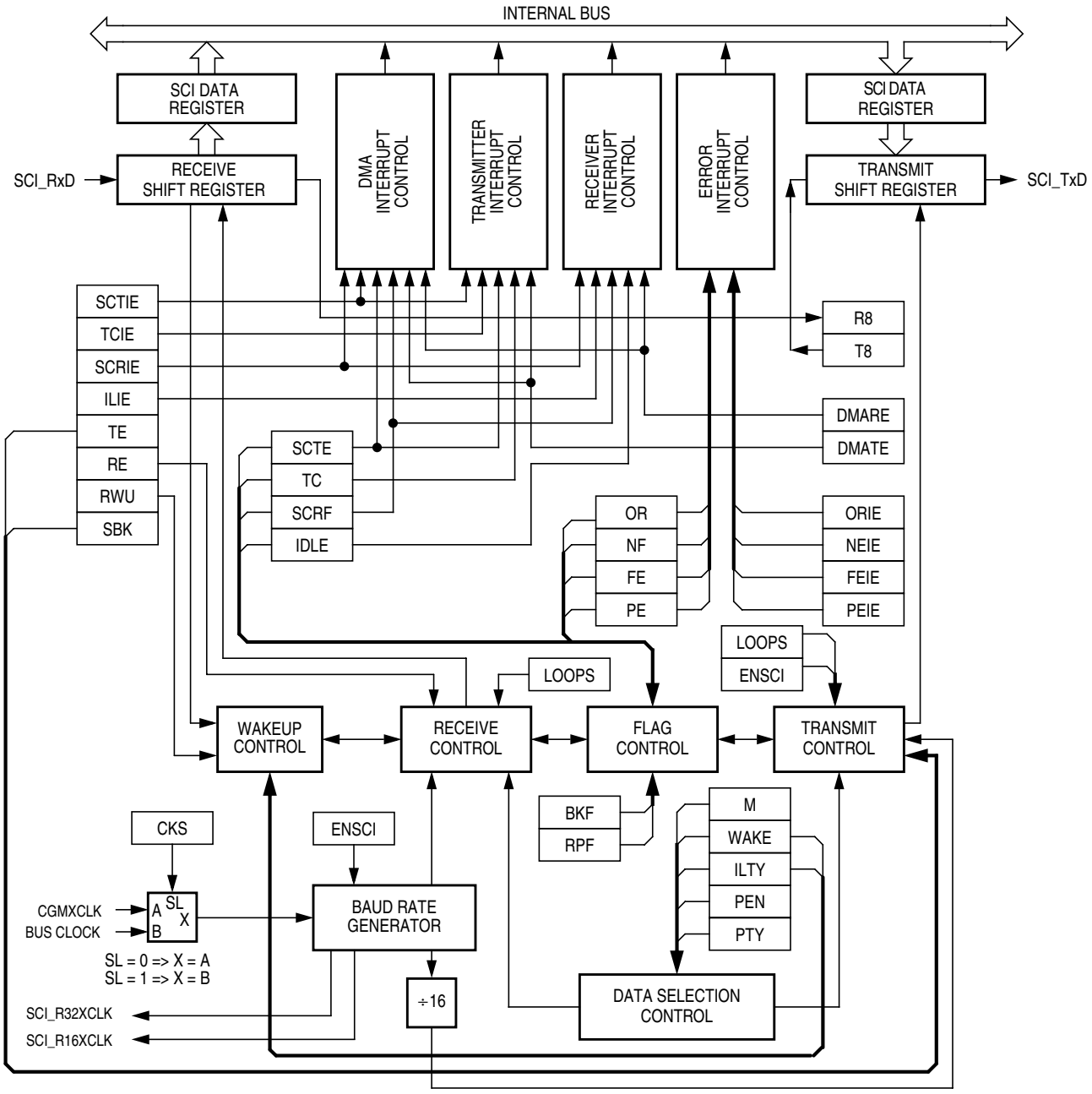


Figure 12-5. SCI Module Block Diagram

NOTE

Writing to the TE bit is not allowed when the enable SCI bit (ENSCI) is clear. ENSCI is in SCI control register 1.

RE — Receiver Enable Bit

Setting this read/write bit enables the receiver. Clearing the RE bit disables the receiver but does not affect receiver interrupt flag bits. Reset clears the RE bit.

1 = Receiver enabled
0 = Receiver disabled

NOTE

Writing to the RE bit is not allowed when the enable SCI bit (ENSCI) is clear. ENSCI is in SCI control register 1.

RWU — Receiver Wakeup Bit

This read/write bit puts the receiver in a standby state during which receiver interrupts are disabled. The WAKE bit in IRSCC1 determines whether an idle input or an address mark brings the receiver out of the standby state and clears the RWU bit. Reset clears the RWU bit.

1 = Standby state
0 = Normal operation

SBK — Send Break Bit

Setting and then clearing this read/write bit transmits a break character followed by a logic 1. The logic 1 after the break character guarantees recognition of a valid start bit. If SBK remains set, the transmitter continuously transmits break characters with no logic 1s between them. Reset clears the SBK bit.

1 = Transmit break characters
0 = No break characters being transmitted

NOTE

Do not toggle the SBK bit immediately after setting the SCTE bit. Toggling SBK before the preamble begins causes the SCI to send a break character instead of a preamble.

12.9.3 IRSCI Control Register 3

IRSCI control register 3:

- Stores the ninth SCI data bit received and the ninth SCI data bit to be transmitted
- Enables the following interrupts:
  - Receiver overrun interrupts
  - Noise error interrupts
  - Framing error interrupts
  - Parity error interrupts

Address: $0042

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	R8	T8	DMARE	DMATE	ORIE	NEIE	FEIE	PEIE
Write:								
Reset:	U	U	0	0	0	0	0	0

= Unimplemented U = Unaffected

Figure 12-14. IRSCI Control Register 3 (IRSCC3)

13.5.3 Transmission Format When CPHA = 1

Figure 13-6 shows an SPI transmission in which CPHA is logic 1. The figure should not be used as a replacement for data sheet parametric information. Two waveforms are shown for SPSCK: one for CPOL = 0 and another for CPOL = 1. The diagram may be interpreted as a master or slave timing diagram since the serial clock (SPSCK), master in/slave out (MISO), and master out/slave in (MOSI) pins are directly connected between the master and the slave. The MISO signal is the output from the slave, and the MOSI signal is the output from the master. The $\overline{SS}$ line is the slave select input to the slave. The slave SPI drives its MISO output only when its slave select input ($\overline{SS}$) is at logic 0, so that only the selected slave drives to the master. The $\overline{SS}$ pin of the master is not shown but is assumed to be inactive. The $\overline{SS}$ pin of the master must be high or must be reconfigured as general-purpose I/O not affecting the SPI. (See 13.7.2 Mode Fault Error.) When CPHA = 1, the master begins driving its MOSI pin on the first SPSCK edge. Therefore, the slave uses the first SPSCK edge as a start transmission signal. The $\overline{SS}$ pin can remain low between transmissions. This format may be preferable in systems having only one master and only one slave driving the MISO data line.

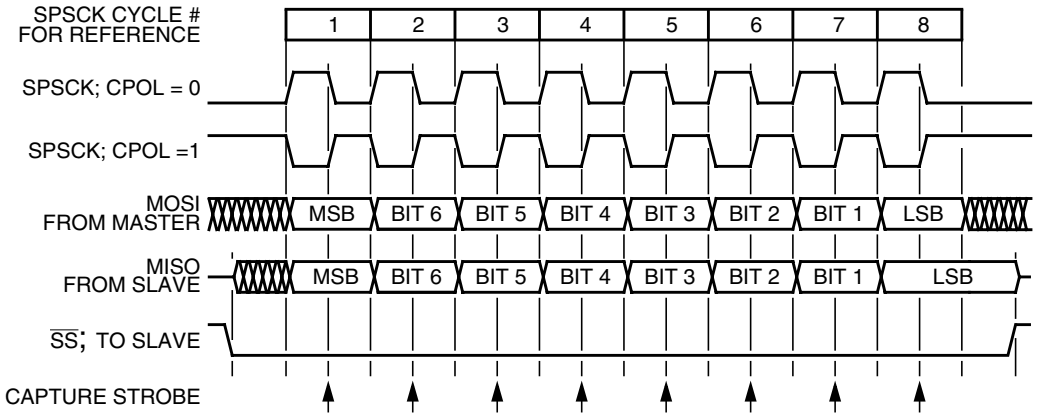


Figure 13-6. Transmission Format (CPHA = 1)

When CPHA = 1 for a slave, the first edge of the SPSCK indicates the beginning of the transmission. This causes the SPI to leave its idle state and begin driving the MISO pin with the MSB of its data. Once the transmission begins, no new data is allowed into the shift register from the transmit data register. Therefore, the SPI data register of the slave must be loaded with transmit data before the first edge of SPSCK. Any data written after the first edge is stored in the transmit data register and transferred to the shift register after the current transmission.

13.5.4 Transmission Initiation Latency

When the SPI is configured as a master (SPMSTR = 1), writing to the SPDR starts a transmission. CPHA has no effect on the delay to the start of the transmission, but it does affect the initial state of the SPSCK signal. When CPHA = 0, the SPSCK signal remains inactive for the first half of the first SPSCK cycle. When CPHA = 1, the first SPSCK cycle begins with an edge on the SPSCK line from its inactive to its active level. The SPI clock rate (selected by SPR1:SPR0) affects the delay from the write to SPDR and the start of the SPI transmission. (See Figure 13-7.) The internal SPI clock in the master is a free-running derivative of the internal MCU clock. To conserve power, it is enabled only when both the SPE and SPMSTR bits are set. SPSCK edges occur halfway through the low time of the internal MCU clock. Since the SPI clock is free-running, it is uncertain where the write to the SPDR occurs relative to the slower SPSCK. This uncertainty causes the variation in the initiation delay shown in Figure 13-7. This delay is no longer than a single SPI bit time. That is, the maximum delay is two MCU bus cycles for DIV2, eight MCU bus cycles for DIV8, 32 MCU bus cycles for DIV32, and 128 MCU bus cycles for DIV128.

14.6.7 MMIIC CRC Data Register (MMCRCDR)

Address: $004E

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	MMCRCD7	MMCRCD6	MMCRCD5	MMCRCD4	MMCRCD3	MMCRCD2	MMCRCD1	MMCRCD0
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 14-10. MMIIC CRC Data Register (MMCRCDR)

When the MMIIC module is enabled, MMEN = 1, and the CRC buffer full flag is set (MMCRCBF = 1), data in this read-only register contains the generated CRC byte for the last byte of received or transmitted data.

A CRC byte is generated for each received and transmitted data byte and loaded to the CRC data register. The MMCRCBF bit will be set to indicate the CRC byte is ready in the CRC data register.

Reading the CRC data register clears the MMCRCBF bit. If the CRC data register is not read, the MMCRCBF bit will be cleared by hardware before the next CRC byte is loaded.

14.6.8 MMIIC Frequency Divider Register (MMFDR)

Address: $004F

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	0	MMBR2	MMBR1	MMBR0
Write:								
Reset:	0	0	0	0	0	1	0	0

= Unimplemented

Figure 14-11. MMIIC Frequency Divider Register (MMFDR)

The three bits in the frequency divider register (MMFDR) selects the divider to divide the bus clock to the desired baud rate for the MMIIC data transfer.

Table 14-2 shows the divider values for MMBR[2:0].

SDA and SCL — Multi-Master IIC Data and Clock

The SDA and SCL pins are multi-master IIC data and clock pins. Setting the MMEN bit in the MMIIC control register 1 (MMCR1) configures the PTB0/SDA and PTB1/SCL pins for MMIIC function and overrides any control from the port I/O logic.

TxD and RxD — SCI Transmit and Receive Data

The TxD and RxD pins are SCI transmit and receive data pins. Setting the ENSCI bit in the SCI control register 1 (SCC1) configures the PTB2/TxD and PTB3/RxD pins for SCI function and overrides any control from the port I/O logic.

T1CH0 and T1CH1 — Timer 1 Channel I/O

The T1CH0 and T1CH1 pins are the TIM1 input capture/output compare pins. The edge/level select bits, ELSxB:ELSxA, determine whether the PTB4/T1CH0–PTB5/T1CH1 pins are timer channel I/O pins or general-purpose I/O pins.

T2CH0 and T2CH1 — Timer 2 Channel I/O

The T2CH0 and T2CH1 pins are the TIM2 input capture/output compare pins. The edge/level select bits, ELSxB:ELSxA, determine whether the PTB6/T2CH0–PTB7/T2CH1 pins are timer channel I/O pins or general-purpose I/O pins.

16.3.2 Data Direction Register B (DDRB)

Data direction register B determines whether each port B pin is an input or an output. Writing a logic 1 to a DDRB bit enables the output buffer for the corresponding port B pin; a logic 0 disables the output buffer.

Address: $0005

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	DDRB7	DDRB6	DDRB5	DDRB4	DDRB3	DDRB2	DDRB1	DDRB0
Reset:	0	0	0	0	0	0	0	0

Figure 16-7. Data Direction Register B (DDRB)

DDRB[7:0] — Data Direction Register B Bits

These read/write bits control port B data direction. Reset clears DDRB[7:0], configuring all port B pins as inputs.

1 = Corresponding port B pin configured as output
0 = Corresponding port B pin configured as input

NOTE

Avoid glitches on port B pins by writing to the port B data register before changing data direction register B bits from 0 to 1.

Figure 16-8 shows the port B I/O logic.